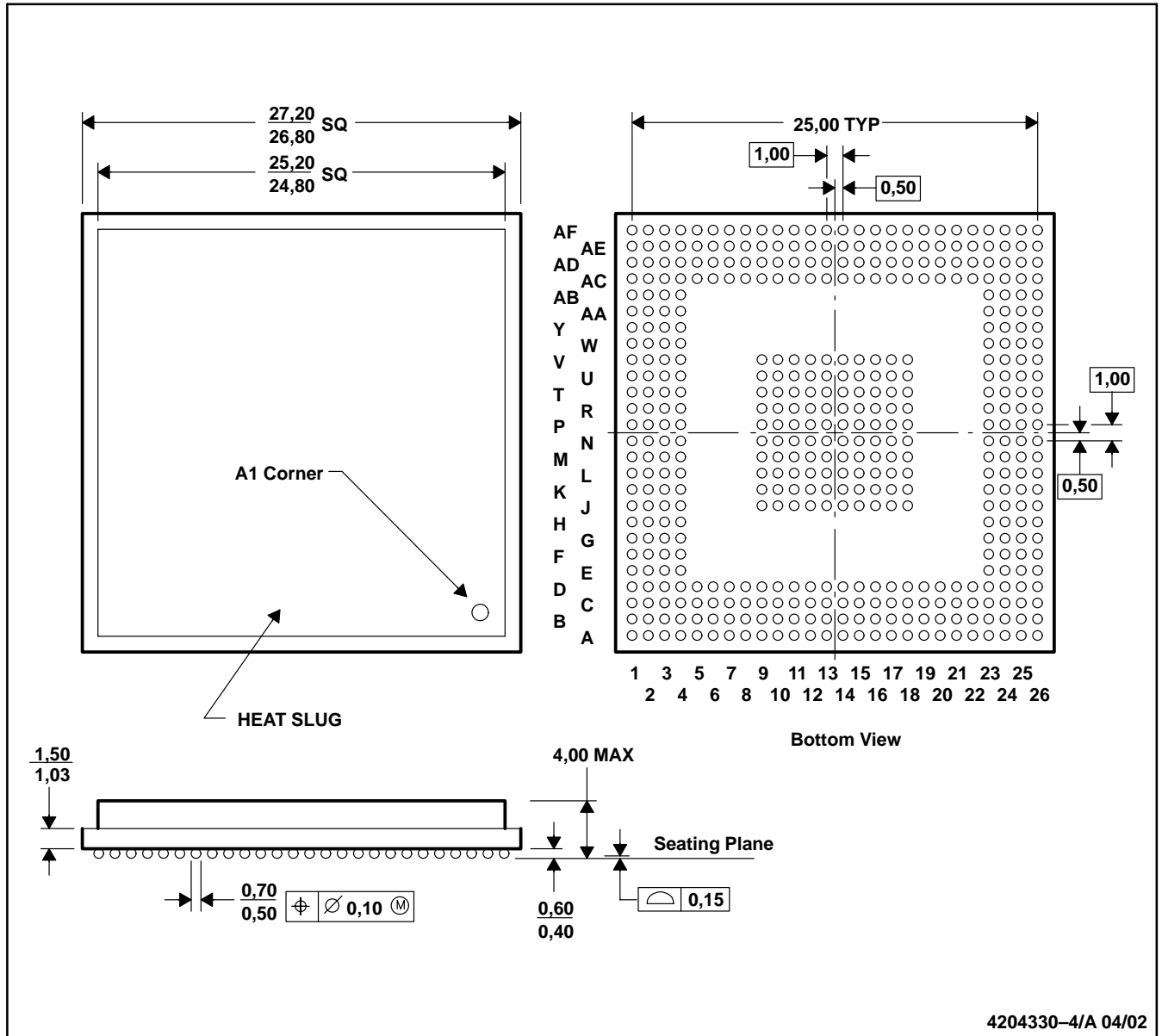


GPY (S–PBGA–N452)

PLASTIC BALL GRID ARRAY



4204330-4/A 04/02

- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Thermally enhanced plastic package with a heat slug (HSL).
 D. Falls within JEDEC MO-151/AAL-1
 E. Flip chip application only.

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